

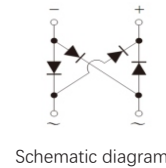
FEATURES:

- Glass Passivated Chip Junction
- High surge forward current capability
- Fast reverse recovery time
- Designed for Surface Mount Application
- Per J-STD-020, LF maximum peak of 260 °C
- Component in accordance to RoHS 2015/863/EU



MECHANICAL DATA

- Case:JBF molded plastic body
- Terminals:Plated leads solderable per MIL-STD-750,method 2026
- Polarity:As marked
- Mounting Position:Any



Marking:

JF :Logo

xxxx Date code

EJBF310:Type

+ -:Polarity

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Ratings at 25°C ambient temperature unless otherwise specified ,Single phase ,half wave ,resistive or inductive load. For capacitive load,derate by 20%.)

Parameter	Symbols	EJBF310	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at $T_c=115^\circ\text{C}$	$I_{F(AV)}$	3.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	100	A
Maximum Forward Voltage at 3.0 A	V_F	1.7	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a=25^\circ\text{C}$ $T_a=125^\circ\text{C}$	I_R	5.0 100	μA
Typical Junction Capacitance (Note1)	C_j	50	pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	40	$^\circ\text{C}/\text{W}$
Maximum Reverse Recovery Time (Note3)	t_{rr}	75	ns
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	$^\circ\text{C}$

Note: 1. Measured at 1 MHz and applied reverse voltage of 4V DC

2. Mounted on glass epoxy PC board with FR4 1.5"X1.5"(3.81X3.81cm) copper pad

3. Measured with $I_F=0.5\text{A}, I_R=1\text{A}, I_{RR}=0.25\text{A}$

Fig.1 Average Rectified Output Current Derating Curve

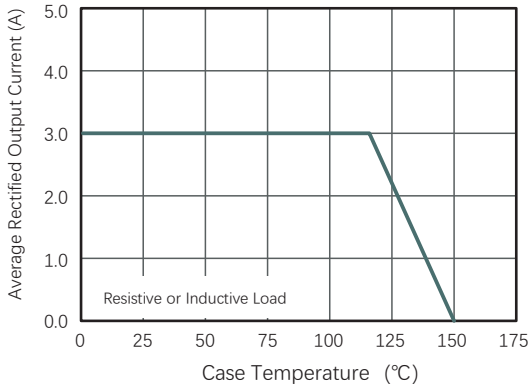


Fig.2 Typical Reverse Characteristics

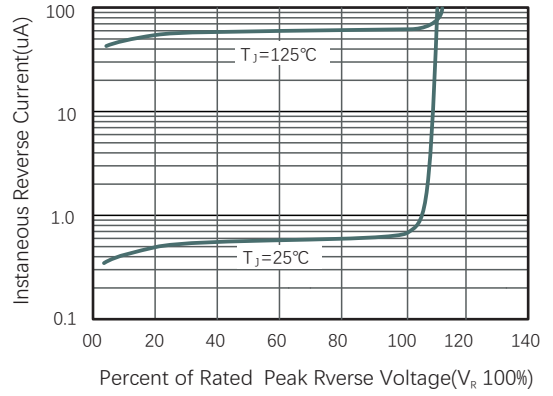


Fig.3 Typical Instantaneous Forward Characteristics

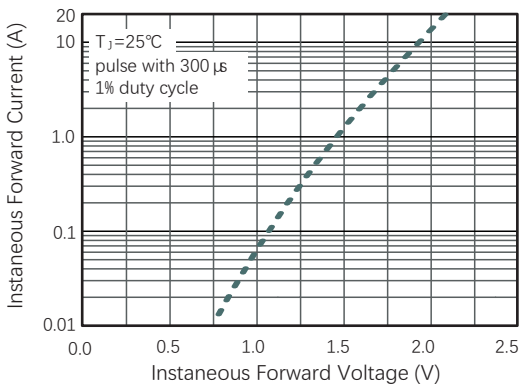


Fig.4 Typical Junction Capacitance

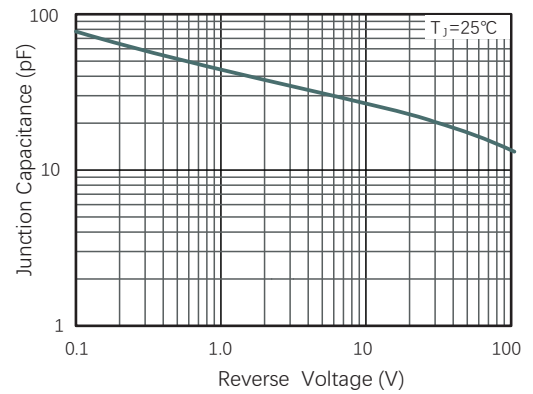
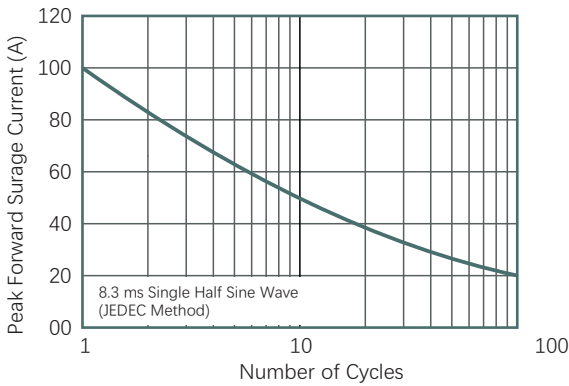
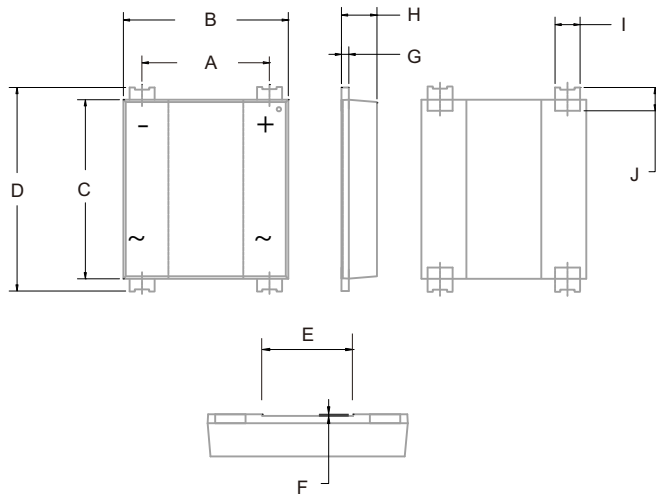


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

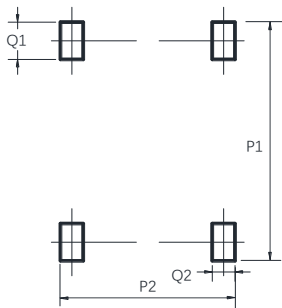


JBF



UNIT:mm		
DIM	MIN	MAX
A	4.80	5.30
B	6.20	7.00
C	7.10	8.20
D	7.90	8.90
E	2.90	3.10
F	0.04	0.08
G	0.15	0.40
H	1.30	1.50
I	0.80	1.20
J	0.70	1.60

Suggested Pad layout



Dimensions in millimeters

Dim	Min
P1	9.15
P2	7.10
Q1	1.80
Q2	2.00

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